

METHOD AND APPARATUS FOR PACKAGING PHOTODETECTORS

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ABSTRACT

15 A method and system for photodetector packaging system is provided with a insulating substrate having a shoulder section and a wire bond is used for coupling the photodetector to the insulating substrate at the shoulder section. The system includes an optical fiber that directs incident light directly to the

20 photodetector. Also provided is a method and system for packaging photodetectors with a insulating substrate using conducting vias and a wire bond to couple the photodetector to the insulating substrate. The system includes conducting tabs that are coupled to the

25 conducting vias. The metal tabs are coupled with a transimpedance amplifier by wire bonds and the

transimpedance amplifier is coupled to a limiting
amplifier by wire bonds.

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